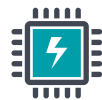


EC900-QCS



Qualcomm® QCS6490
Ultra Small Size Embedded System

KEY FEATURES



Qualcomm

Qualcomm QCS6490 high-level platform



High Speed Memory Down

LPDDR5x on board memory up to 8G



Multiple Expansions

1 M.2 E key 2230, 1 M.2 B key 3052



Rich I/O

2 USB 3.1, 1 GbE LAN, 1 HDMI, 1 Audio Jack,
1 COM, 8 bit DIO



AMR

Target on AMR, box PC application



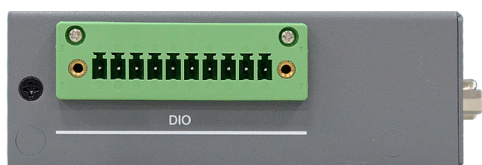
PANEL



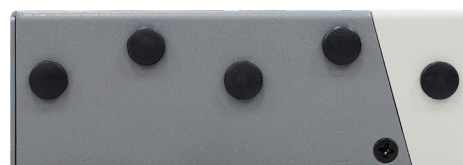
Front View



Rear View



Left View



Right View

SPECIFICATION

PLATFORM	Platform	ARM
SYSTEM	Processor	QCS6490 Qualcomm® Kryo™ 670, 8 cores, up to 2.7 GHz, 12 TOPS (INT8)
	Memory	LPDDR5x, 4/8GB
GRAPHICS	Display	1 x HDMI Type A, w/audio. 1080P support on Linux.
	Single Display	HDMI
STORAGE	External / Internal	Support UFS 3.1, default 128GB 1 x uSD3.0 card
EXPANSION	Interface	1 x M.2 B key 3052 (USB 3.1/ Opt. USB 2.0) 1 x M.2 E key 2230 (PCIe x1) 1 x Nano SIM slot
ETHERNET	Controller	AX88179A USB3 to GbE controller
LED	Indicators	1 x Status LED
I/O	Ethernet	1 x GbE (RJ-45)
	Serial	1 x RS-232
	USB	2 x USB 3.1 Gen1 Type A
	Display	1 x HDMI 1.4
	WiFi/LTE Antenna	3 x Antenna Holes
	DIO	8 bit DIO (Via Terminal block, Default 6 DIO)
INTERNAL I/O	USB	3 x USB 2.0 (UBJ1/2/4, 1x4P/1.25mm), UBJ4 could option to M.2 B key 1 x USB Type C (Download only)
	Serial	2 x RS-232
POWER	Type	5VDC
	Connector	2 pin Power Jack
	Consumption	Typical: QCS6490: 5V @ 0.6A (3.0Watt) Max.: QCS6490: 5V @ 1.45A (7.25Watt)
OS SUPPORT	Os Support	Default: Yocto (Linux Kernel 6.6.x) Upon request: Ubuntu 20.04 (Linux Kernel 5.4.x)
MECHANISM	Construction	Sheet Metal
	Mounting	DIN Rail Mount
	Dimensions (W x H x D)	145mm x 34mm x 96mm
	Weight	TBD
ENVIRONMENT	Operating Temperature	-20~60°C
	Storage Temperature	-40 to 85°C
	Relative Humidity	10 to 95% RH (non-condensing)
STANDARDS AND CERTIFICATIONS	Shock	Operating: 3G, 11ms Non-Operating: 5G, 11ms
	Vibration	Operating: Random 5~500Hz, IEC68-2-64 (3G) Non-Operating: Sine 10~500Hz, IEC68-2-6 (3G)
	Certification	CE, FCC Class A, UKCA, RoHS